

SALFLEX 180

Characteristics		
Conductor material	Copper	Aluminium
Thermal class (temperature index)	Cu: H (180 °C)	AI: H (180 °C)
Chemical composition Base resins Overcoat Bonding coat	Modified polyurethanes - -	
Reference to the International Standards	Copper	Aluminium
	IEC 60317-51 NEMA MW 1000 spec. MW 82-C	IEC 60317-51 NEMA MW 1000 spec. MW 82-C
UL - approval	File E 60641	
Diameters range grade 1 (L) grade 2 (2L)	Copper	Aluminium
	Ø 0,018 ÷ 2,240 mm Ø 0,050 ÷ 1,800 mm	Ø 0,150 ÷ 0,630 mm Ø 0,150 ÷ 0,630 mm
Cut-through temperature Ø 0,050 mm Ø 0,500 mm	Higher than 240 °C Higher than 260 °C	
Heat shock to IEC standard Ø 0,300 mm Ø 0,500 mm	230 ÷ 240 °C 220 ÷ 230 °C	
Significant properties	• Directly solderable without any prior mechanical stripping of the enamel at the temperature: Ø 0,050 mm at 370 \div 390 °C in 1" Ø 0,500 mm at 380 \div 400 °C in 2"	
	 Due to a good surface smoothness and copper softness it is excellent for fine wire windings requiring high filling factor Good thermal resistance (180 °C) Good mechanical resistance Excellent resistance to sizing of epoxied and polyamide resins 	
Recommended applications	It is especially suitable for applications requiring automated soldering systems: small transformers, small motors, measuring equipment, impregnated and unimpregnated coils operating at a max. temperature of 180 °C	

